



#### **DUAL N-CHANNEL ENHANCEMENT MODE MOSFET**

### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = 25°C
30V	$20m\Omega$ @ $V_{GS} = 10V$	10A

### **Description and Applications**

This MOSFET has been designed to minimize the on-state resistance  $(R_{DS(on)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- General Purpose Interfacing Switch
- Power Management Functions
- DC-DC Converters
- Analog Switch

## **Features and Benefits**

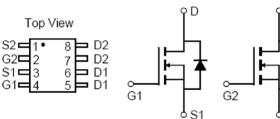
- N-Channel MOSFET
- Low On-Resistance
- Low Input Capacitance
- Low Input/Output leakage
- Low Gate Resistance
- Fast Switching Speed
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Qualified to AEC-Q101 standards for High Reliability

### **Mechanical Data**

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish NiPdAu over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Weight: 0.072 grams (approximate)







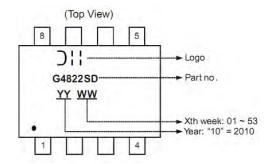
### **Ordering Information (Note 3)**

Part Number	Case	Packaging
DMG4822SSD-13	SO-8	2500/Tape & Reel

Notes:

- 1. No purposefully added lead.
- 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com.
- 3. For packaging details, go to our website at http://www.diodes.com.

## **Marking Information**





## **Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic			Symbol	Value	Units
Drain-Source Voltage			$V_{DSS}$	30	V
Gate-Source Voltage			$V_{GSS}$	±25	V
Continuous Drain Current (Note 4) V <sub>GS</sub> = 10V	Steady State	$T_A = 25^{\circ}C$ $T_A = 85^{\circ}C$	I <sub>D</sub>	10 6.6	А
Pulsed Drain Current (Note 5)			I <sub>DM</sub>	60	Α
Avalanche Current (Note 6) (Note 7)			I <sub>AR</sub>	1.68	А
Repetitive Avalanche Energy L= 0.3mH (Note 6) (Note 7)			$E_{AR}$	12.8	mJ

# **Thermal Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

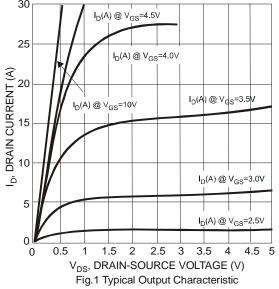
Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 4)	$P_{D}$	1.42	W
Thermal Resistance, Junction to Ambient (Note 4)	$R_{ hetaJA}$	88.4	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

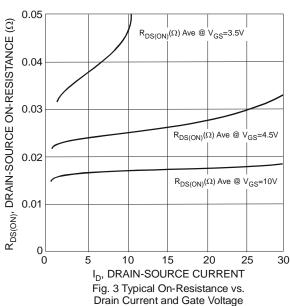
## Electrical Characteristics @TA = 25°C unless otherwise specified

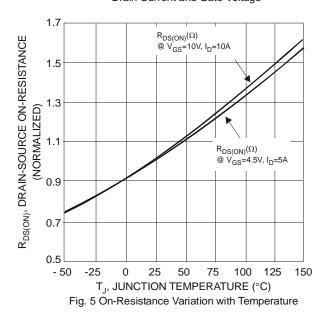
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	-	-	٧	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	-	-	1	μΑ	$V_{DS} = 30V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	-	-	±100	nA	$V_{GS} = \pm 25V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)						_	
Gate Threshold Voltage	$V_{GS(th)}$	1.0	-	3.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance		1	13.4	20.0	mΩ	$V_{GS} = 10V, I_D = 8.5A$	
Static Dialit-Source Off-Resistance	R <sub>DS</sub> (ON)	-	19.5	31.0	11122	$V_{GS} = 4.5V, I_D = 6A$	
Forward Transfer Admittance	Y <sub>fs</sub>	1	20	-	mS	$V_{DS} = 5V, I_{D} = 8.5A$	
Diode Forward Voltage (Note 8)	V <sub>SD</sub>	-	0.4	1.0	V	$V_{GS} = 0V, I_{S} = 1A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	-	478.9	-	pF	V <sub>DS</sub> = 16V, V <sub>GS</sub> = 0V, -f = 1.0MHz	
Output Capacitance	Coss	-	96.7	-	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	61.4	-	pF		
Gate resistance	$R_g$		1.1		Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg		5.0	-	nC		
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	-	10.5	-	nC	$V_{GS} = 10V, V_{DS} = 15V,$	
Gate-Source Charge	Q <sub>gs</sub>	-	1.8	-	nC	I <sub>D</sub> =8.5A	
Gate-Drain Charge	Q <sub>gd</sub>	-	1.6	-	nC		
Turn-On Delay Time	t <sub>D(on)</sub>	-	2.9	-	ns		
Turn-On Rise Time	t <sub>r</sub>	-	7.9	-	ns	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 10V,	
Turn-Off Delay Time	t <sub>D(off)</sub>	-	14.6	-	ns	$R_L = 1.8\Omega$ , $R_G = 3\Omega$ ,	
Turn-Off Fall Time	t <sub>f</sub>	-	3.1	-	ns		

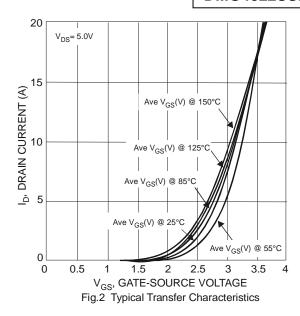
- 4. Device mounted on FR-4 PCB, with minimum recommended pad layout.
- 5. Device mounted on minimum recommended pad layout test board, 10µs pulse duty cycle = 1%
- Device mounted on minimum recommended pad layout test board, Tops pulse to Repetitive rating, pulse width limited by junction temperature.
  I<sub>AR</sub> and E<sub>AR</sub> rating are based on low frequency and duty cycles to keep Tj=25°C
  Short duration pulse test used to minimize self-heating effect.
  Guaranteed by design. Not subject to product testing.

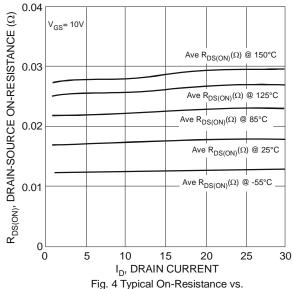












Drain Current and Temperature

0.06  $R_{DS(ON)}$ , DRAIN-SOURCE ON-RESISTANCE  $(\Omega)$ 0.05  $\mathsf{R}_{\mathsf{DS}(\mathsf{ON})}(\Omega)$ 0.04 @ V<sub>GS</sub>=4.5V, I<sub>D</sub>=5A 0.03 0.02  $R_{DS(ON)}(\Omega)$ @ V<sub>GS</sub>=10V, I<sub>D</sub>=10A 0.01 0 - 50 25 50 75 100 125 T<sub>J</sub>, JUNCTION TEMPERATURE (°C)



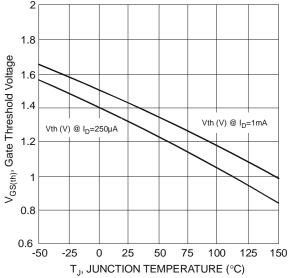


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

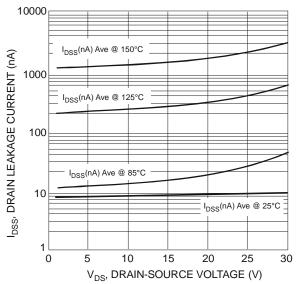
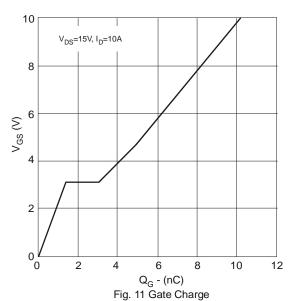
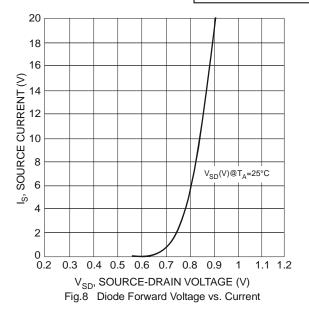
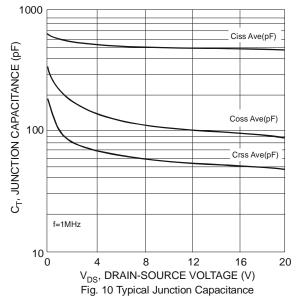


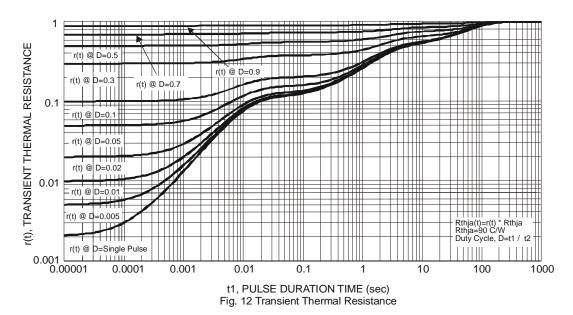
Fig. 9 Typical Drain-Source Leakage Current vs. Voltage



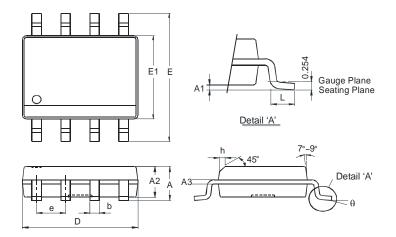






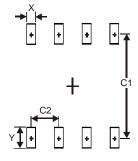


# Package Outline Dimensions



SO-8				
Dim	Min	Max		
Α	-	1.75		
A1	0.10	0.20		
A2	1.30	1.50		
А3	0.15	0.25		
b	0.3	0.5		
D	4.85	4.95		
Е	5.90	6.10		
E1	3.85	3.95		
е	e 1.27 Typ			
h	-	0.35		
L	0.62	0.82		
θ	0°	8°		
All Dimensions in mm				

# **Suggested Pad Layout**



Dimensions	Value (in mm)
Х	0.60
Υ	1.55
C1	5.4
C2	1.27



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